

METHOD AND SYSTEM FOR ENHANCEMENT OF WAFER ALIGNMENT ACCURACY

ABSTRACT OF THE DISCLOSURE

A computer method of corrects position data defining the location of alignment marks on a workpiece. The steps begin with scanning marks along a first direction to determine direction wafer scaling along the first direction. Then, scanning marks along a second direction to determine direction wafer scaling along the second direction. Next, scan a first set of alignment marks on a workpiece oriented in a first direction and a second set of alignment marks on a workpiece oriented in a second direction in an initial sequence to collect initial direction data on the location. Then scan the first set of alignment marks and the second set of alignment marks in a reverse sequence to collect reverse direction data on the location. Then average the initial direction data and the reverse direction data. Thus, false alignment data attributable to false measured locations of alignment marks is corrected.

(FIGURE 1 IS SUGGESTED FOR PUBLICATION)